



Date: November 12, 2003

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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>	ATTY. DOCKET NO. INDUM-110XX	APPLICATION NO. 10/636,105
	APPLICANT: Wushing Yin, et al.	
	FILING DATE 8/7/03	TC ART UNIT 3726

U.S. PATENT DOCUMENTS

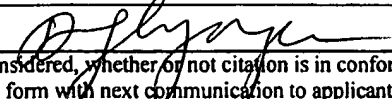
EXAMINER INITIAL	DOCUMENT NUMBER	PUBLICATION/ ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE
DN	US2003/0096452	5/22/2003	Yin, et al.	438	108	
	US2003/0096453	5/22/2003	Wang, et al.	438	108	
	US2003/0109080	6/12/2003	Dias	438	108	
	US5,128,746	7/7/1992	Pennisi, et al.	357	72	
	US6,038,136	3/14/2000	Weber	361	783	
	US6,157,086	12/5/2000	Weber	257	788	
DN	US6,168,972	1/2/2001	Wang, et al.	438	108	
	US6,457,828	11/5/2002	Hoang	438	108	
DN	US6,506,681	1/14/2003	Grigg, et al.	438	692	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
DN	WO 99/56312	11/4/1999	WIPO			X	

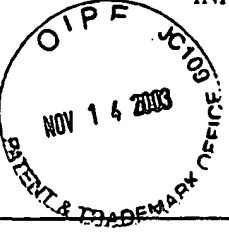
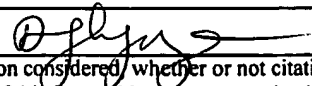
OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)

DN	Product Data Sheet; "Epoxy Flip Chip Flux PK-001"; Indium Corporation of America
DN	Product Data Sheet; "Pb-Free Epoxy Flip Chip Flux PK-002"; Indium Corporation of America
DN	Surface Mount Technology; Materials, Processes and Equipment; Carmen Capillo; Unisys Corporation; San Jose, CA

EXAMINER 	DATE CONSIDERED 11/17/03
*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

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	US						
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FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO	
OTHER DOCUMENTS <i>(including Author, Title, Date, Pertinent Pages, etc.)</i>							
DN	"No Flow Underfill Reliability is Here - Finally?"; Michael A. Previti; Cookson Semiconductor Packaging Materials; Alpharetta, GA						
DN	"The Development of No-Flow Underfill Materials for Flip-Chip Applications"; Dr. C. P. Wong; S. H. Shi; School of Materials Science and Engineering & Packaging Research Center; Georgia Institute of Technology; February 2, 1999						
DN	"No-Flow Underfill Materials for Environment Sensitive Flip-Chip Process; A Dissertation Presented to The Academic Faculty; Zhuqing Zhang; Georgia Institute for Technology; June 2001 Chi Flfor						
DN	"A Novel Approach to Incorporate Silica Filler into No-Flow Underfill"; Zhuqing Zhang, Jicum Lu; C. P. Wong; School of Materials Science and Engineering and Packaging Research Center; Georgia Institute of Technology; Georgia; Pages 1-7						
EXAMINER				DATE CONSIDERED			
				10/17/05			
*EXAMINER: Initial if citation considered/whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							